



AF 2814
224

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the Application of

DONALD C. ABBOTT ET AL.

Serial No. 10/724,498 (TI-28098.1)

Filed: December 1, 2003

For: SEMICONDUCTOR CIRCUIT ASSEMBLY HAVING PLATED LEADFRAME
INCLUDING GOLD SELECTIVELY COVERING AREAS TO BE SOLDERED

Art Unit 2814

Examiner Wael M. Fahmy

Customer No. 23494

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3-31-06

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Jay M. Cantor, Reg. No. 19,906

AMENDMENT UNDER 37 C.F.R. 1.116

Dear Sir:

In response to the Office action dated March 22, 2006, the following remarks are presented: